



产品编码 P/N	PSDPAA Series	测试设备 TEST INSTRUMENT	Chroma 3302 16502
产品系列 Series	双路耦合功率电感 SMD Molding Coupled Power	测试频率 TEST FREQUENCY	100KHZ/1V

客户名称

Customer

客户编码

Customer P/N

产品系列

Series

双路耦合功率电感

SMD Molding Coupled Power Inductor

产品编码

Supply P/N

PSDPAA Series

发版号

Version

4.0

承认日期

Endorsement Date

2025-7-4

备注

Note

客户承认

Customer Approval

谱罗德电子科技（深圳）有限公司

PuLuoDe Electronic Technology (Shenzhen) Co. LTD

制作

APPROVED

Ben

审查

CHECKED

Yuki

确认

PREPARED

Peter

客户签章



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产品特点

Features

- ☐ 多种电路拓扑结构，节省PCB空间
Multiple circuit topology methods and save PCB space
- ☐ 较高的额定电流，低直流阻抗
High rated current ,low DCR
- ☐ 具有耦合电感与共模电感双重特性
It has dual characteristics of coupled inductance and common mode inductance
- ☐ 可用于SEPIC, Zeta, Flyback等拓扑电路
can be applied to SEPIC,Zeta, flyback and other topological circuit
- ☐ 金属一体结构，屏蔽性好，耦合性更佳
Molded one-piece structure、Good magnetic shielding、High coupling efficiency

编码解释

Code interpretation

PSDPAA	XXXX	-	XXX	M	ANP
类别码	尺寸系列		系列码	公差	特征识别码
Category code	Dimension		Inductance	Tolerance	Feature Code

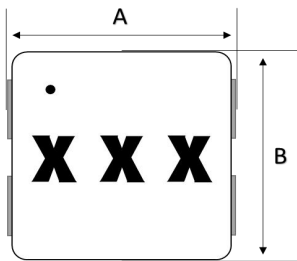
- ◎ 规格参数基于环境温度25℃取得
All test Data is referenced to 25℃ ambient
- ◎ 电感工作环境温度：-40℃ ~ 125℃
Operating temperature range -40 °C to +125 °C
- ◎ 加载温升电流（Irms）会使电感温度上升大约 40℃（电感初始温度+上升温度=电感最终温度）
Typical Irms would cause an approximately ΔT of 40℃
- ◎ 加载饱和电流（ISAT）会使感量下降大约30%
Typical ISAT would cause Lo to drop approximately 30%.
- ◎ 请从温升电流（IRMS）和饱和电流（ISAT）中选取一个最小值作为额定电流
The rated current shall refer to the minimum ISAT and IRMS current
- ◎ 务必考虑最终的产品设计，元器件布局，线路板走线，以及使用环境过程中，电感最终温度不得超过125℃
The operating temperature of inductance do not exceed 125℃
- ◎ 使用电感时，请查阅第8页注意事项
The announcements is on page 8



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封装尺寸 Dimension (mm)

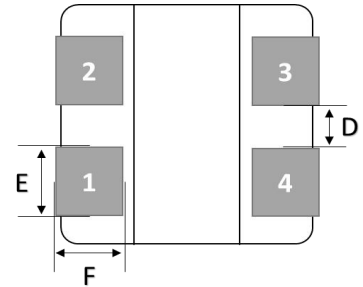
俯视图
Top view



侧视图
Side view



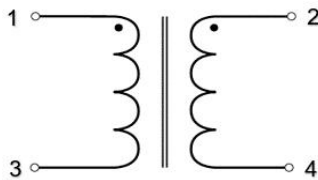
底视图
Bottom view



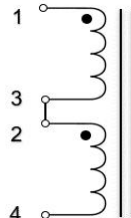
系列 Series	封装尺寸 Dimension					
	A	B	C	D	E	F
1080	11.2 ± 0.5	10.2 ± 0.3	8.0 MAX	1.6 Ref	3.1 Ref	2.4 Ref

电路拓扑 Schematics

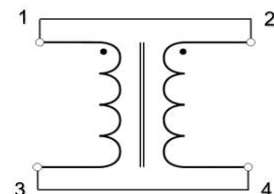
Schematics



双电感/Duai Inductor



串联/Series



并联/Parallel

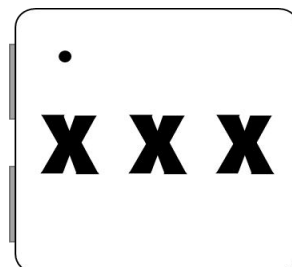
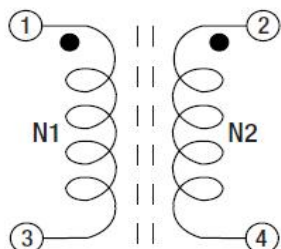
1080 Series

产品编码 P/N	@ 25 °C Ambient Temperature					
	感值 Inductance	公差 Tolerance	DCR		温升电流 (IRMS)	饱和电流 (ISAT)
			mΩ		A	A
	μH	±	Typ	Max	ΔT ≈ 40°C	L0 drop ≈ 30%
PSDPAA1080-100M-ANP	10	20%	35	45	8	12
PSDPAA1080-150M-ANP	15	20%	50	59	4.5	9
PSDPAA1080-220M-ANP	22	20%	75	85	3	7
PSDPAA1080-330M-ANP	33	20%	115	130	2.6	7
PSDPAA1080-470M-ANP	47	20%	145	160	2.5	6

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电路结构

Connections

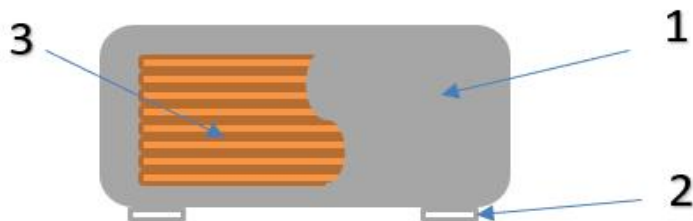


◎ 电感内置两组线圈
Inductor Contents two (2) Set(s) of Coil

电感喷码印字：黑色 “.XXX”
Marking:Black ".xxx"

产品结构

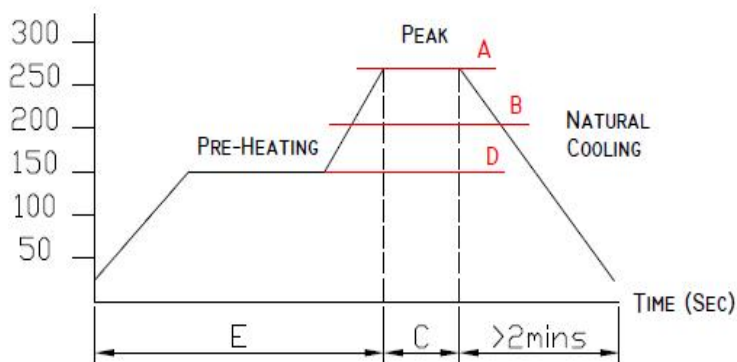
Product Structure



- 1: 磁芯 / Core
- 2: 电极 / Electrode
- 3: 线圈 / coil

焊接温度（推荐）

Recommended Soldering Temperature Graph



A	260°C
B	230°C
C	10 Sec
D	150°C
E	60~240 Sec



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机械可靠性测试

Mechanical Reliability

实验名称 ITEM	试验要求 Specification & Requirement	试验方法 Method Used
可焊性实验 Solderability	The surface of terminal/pin tested shall be covered with new solder by 95%	Solder heat proof: Preheating: 180 ±10°C 90 seconds Soldering: 255 ±5°C for 3 ±1 sec
机械冲击 Shock	Inductance change within ± 5% Without mechanical damage SMD Molding Indu	Drop down with 981m/s2 (100G) shock Attitude upon a rubber block method shock testing machinem, 3 tests.
振动实验 Vibration	Inductance change within ± 5% Without mechanical damage	Vibration frequency: 10Hz to 55Hz to 10Hz 60 seconds cycle Vibration time: 2 hours

老化测试

Aging Reliability

实验名称 ITEM	试验要求 Specification & Requirement	试验方法 Method Used
冷热冲击 Thermal Shock	Inductance change within ± 5% Without mechanical damage	-55°C, (30 mins) -> room temp. (5 mins) -> 125°C, (30 mins) -> room temp. (5 mins) 100 cycles
耐热性 Heat Resistance	Inductance change within ± 5% Without mechanical damage	Apply IDC current @ 85°C ambient Duration: 1000 hrs
耐湿性 Humidity Resistance	Inductance change within ± 5% Without mechanical damage	Apply IDC current @ 60°C ambient Humidity: 90~95% Duration: 1000 hrs
低温存储实验 Low Temp. Storing	Inductance change within ± 5% Without mechanical damage	Storing Temp. -55 ±2 °C for total 1,000 +4/-0 hours
高温存储实验 High Temp. Storing	Inductance change within ± 5% Without mechanical damage	Storing Temp. 125 ±2 °C for total 1,000 +4/-0 hours

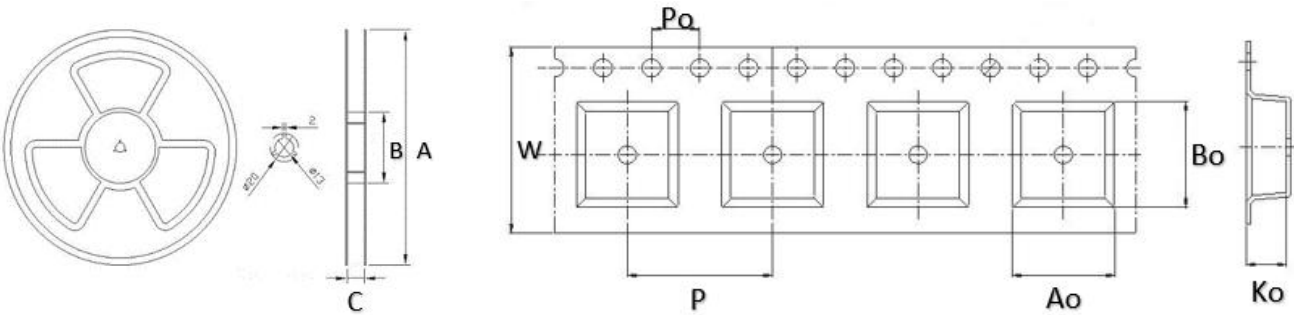


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载带卷盘尺寸 : (mm)

Packing Dimension

MPQ	A	B	C	W	P	Po	Ao	Bo	Ko
400pcs/卷盘	330	21	13	24	16	4	10.7 Ref	11.8 Ref	8.5 Ref

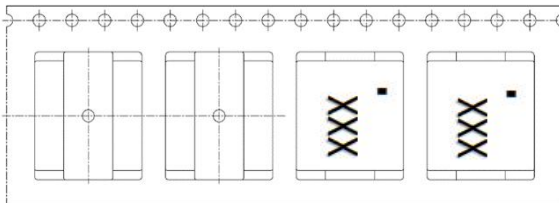


载带内产品排列方式:

Inductance Packing Method

首字对孔

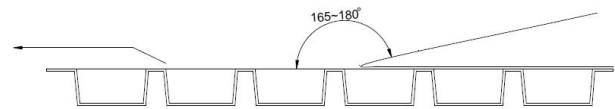
The first mark is on the side of the gear hole



载带剥离力:

Typical Pulling Force

20~120 gf



装箱数量:

Package Quantity

400pcs/卷盘

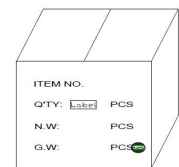
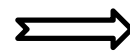
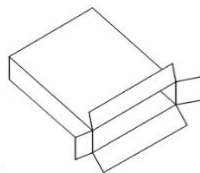
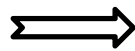
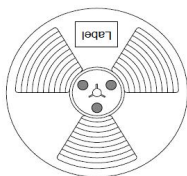
400pcs/Reel

800pcs/每盒

800pcs/ Middle box

2400pcs/每箱

2400pcs/ Outer box



© 实际出货过程, 依据客户需求状况的不同, 包装数量会有变化, 最终的包装数量请参照实际出货包装

In the actual delivery process, the package quantity will change according to the different customer demands. Please refer to the actual shipment quantity for the final package quantity





注意事项

使用本产品时，请注意以下事项

- ◎ 产品保存期限为12个月，保存条件：温度5~40℃，湿度10~75%RH以内，超过保存期限可能会使元器件电极发生氧化，存储标准可参照：IEC_61760-2-2021
This components storage life is 12 months, Storage Temperature: TEMP.5~40℃; RH10%~75%. Please use this components within the warranty period. refer standard to: IEC_61760-2-2021
- ◎ 请勿在极端环境下使用和保存（高盐，强酸，强碱，强辐射等）。
Do not use this component in special environments, such as high salt content, strong acid, strong alkali, strong corrosion and other special environments.
- ◎ 元器件焊接前，请进行预热，预热与焊接温度之间温差建议控制在150℃以内；焊接标准参考：EN61760-1:2006
Please preheat the product before welding; it is recommended to control the preheating temperature and welding temperature within 150℃. refer standard to: EN61760-1:2006
- ◎ 元器件焊接后需重新拆卸焊接修正时，请遵循规格书规定的条件范围；过高的加热温度以及反复的拆卸可能会导致元器件失效。
When repairing this component, the temperature used for disassembly should not exceed the datasheet limit and do not disassemble it frequently to prevent damage to the component.
- ◎ 请勿用清洗剂、丙酮等腐蚀性液体接触该元器件，这可能会侵蚀元器件本体以至于失效。
Do not use acetone or other corrosive liquids to contact this component or it will cause it to fail.
- ◎ 元器件焊接到线路板后，请注意不可因线路板整体变形或局部变形而施加给电感剩余应力，这可能会导致元器件脱落、破损失效。
When this component is soldered to the circuit board, you need to pay attention to the stress applied to it by the PCB, which may cause it to fall off or damaged fail.
- ◎ 元器件通电后温度会随电流的增大而上升，设计时请务必考虑留有余量。
Self heating (Rated Current or Irms) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- ◎ 过高的静电会损坏该元器件，请注意静电防护。
Too high static electricity will cause permanent damage to the product, please pay attention to electrostatic protection.
- ◎ 本元器件作为磁性产品，设计时请务必考虑周边元器件与本产品可能产生的耦合效应影响。
This magnetic component needs to be considered for coupling effects in the application.
- ◎ 谱罗德并不能完全掌握或熟悉客户的特定应用以及要求，贵司有责任和义务验证此元器件以及元器件规格书中的描述是否满足于贵司的设计要求；需要指出是：即使按照现有的技术标准操作，该元器件依然有几率在典型寿命结束前发生故障，谱罗德强烈建议贵司对于该元器件在一些典型的严苛应用中，例如安规产品，工业产品、医疗产品、车载产品、航空/航天等产品应用，对于该元器件可能存在的失效情况做适当的冗余设计，以此避免该元器件在失效时造成严重后果；特别提醒：对于特定的应用对象谱罗德强烈要求贵司同谱罗德取得书面的许可，否则谱罗德不予承担元器件失效带来的任何责任，特定对象包括且不限于：车用，航空航天，安规产品，军用以及贵司对元器件有严苛要求的产品。

PROD cannot fully understand and be familiar with customers' specific applications and requirements. Your company has the responsibility and obligation to verify whether the components and the description in the component specification meet your design requirements. Special reminder: Even if operated in accordance with existing technical standards, this component still has a chance of failure before the end of its typical life. PROD strongly recommends that your company make appropriate redundant designs for possible failure situations of this component in some typical harsh applications, such as safety products, industrial products, medical products, automotive products, aviation/aerospace products, etc., so as to avoid serious consequences when the component fails.

PROD Requirements: For specific application item, PROD strongly requires your (or company) to obtain written permission from PROD, otherwise PROD will not bear any responsibility for component failure. Specific item list include but are not limited to: automotive, aerospace, safety products, military and products that your company has strict requirements on components.

